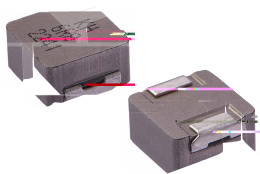


MDA HT Series

SMD Moulded Inductor

Size 1040



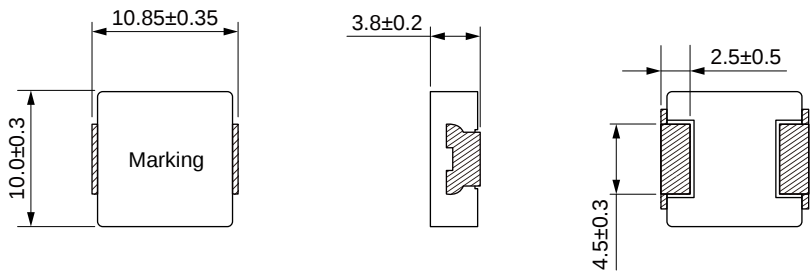
FEATURES

-
-
-
-
-

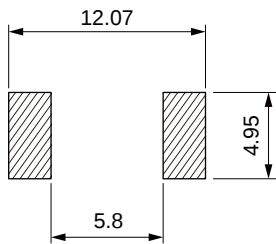
APPLICATION

-
-
-

Dimensions: [mm]



Land Pattern: [mm]

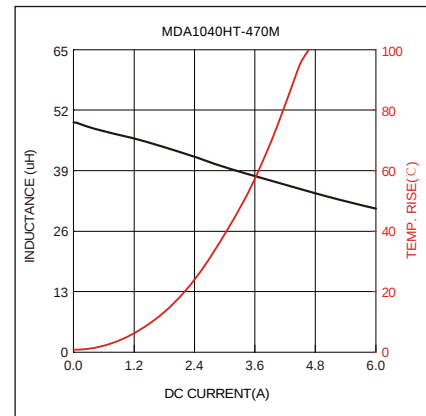
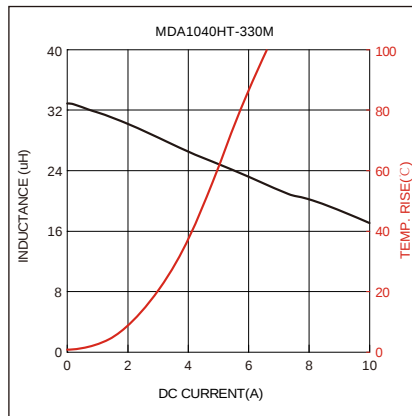
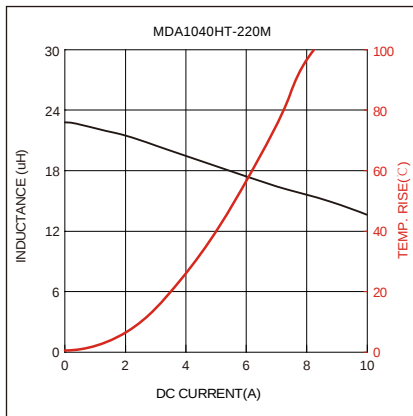
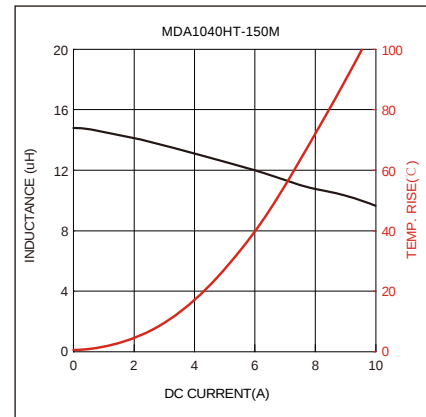
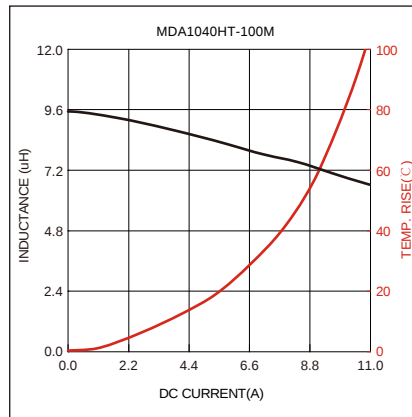
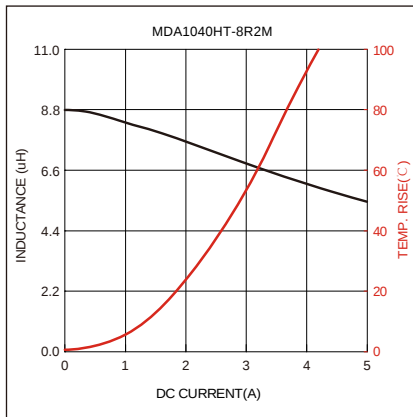
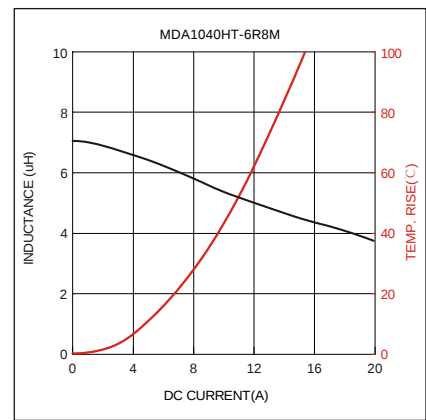
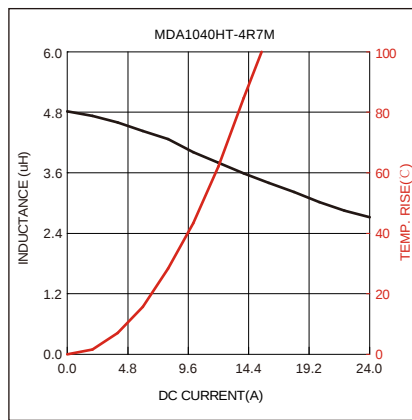
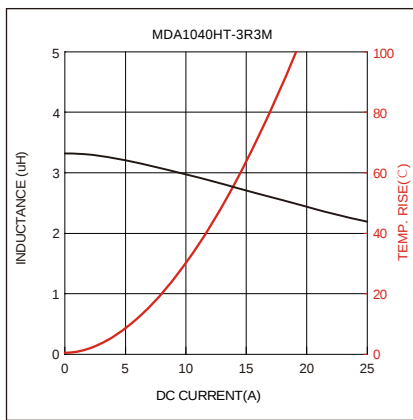
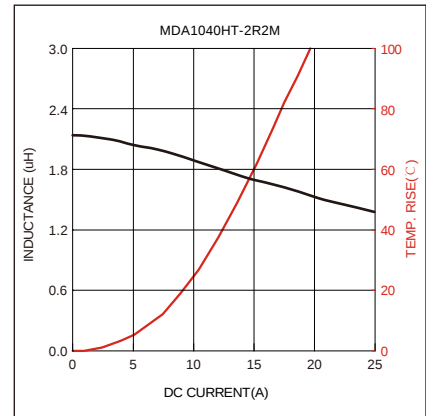
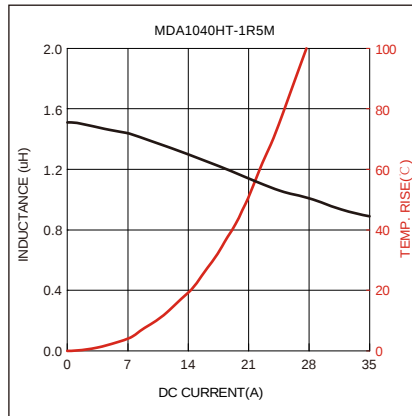
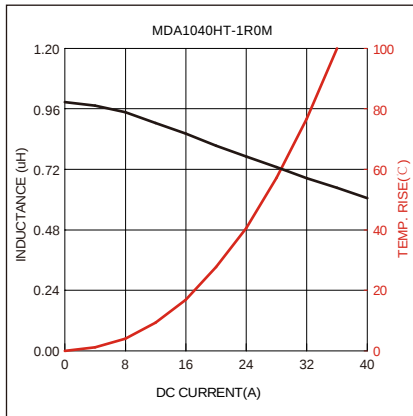


Electrical Properties:

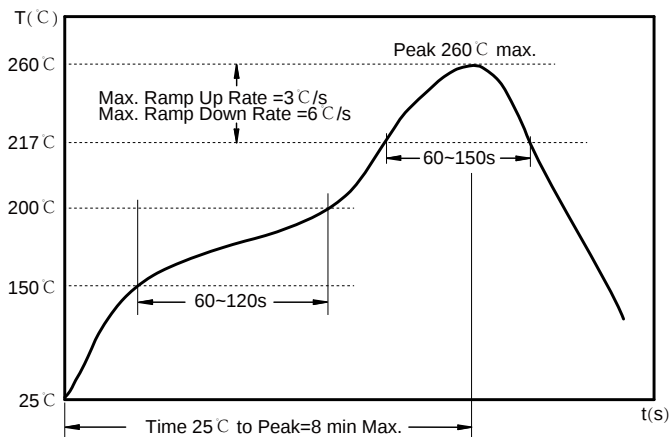
	(μ H)		(A)	(A)	Satura on (A)	Satura on (A)	(m Ω)



Typical Electrical Characteristics:



Soldering Reflow:



Preheat condition: 150 ~200 °C / 60~120 sec.

Allowed time above 217 °C : 60~150 sec.

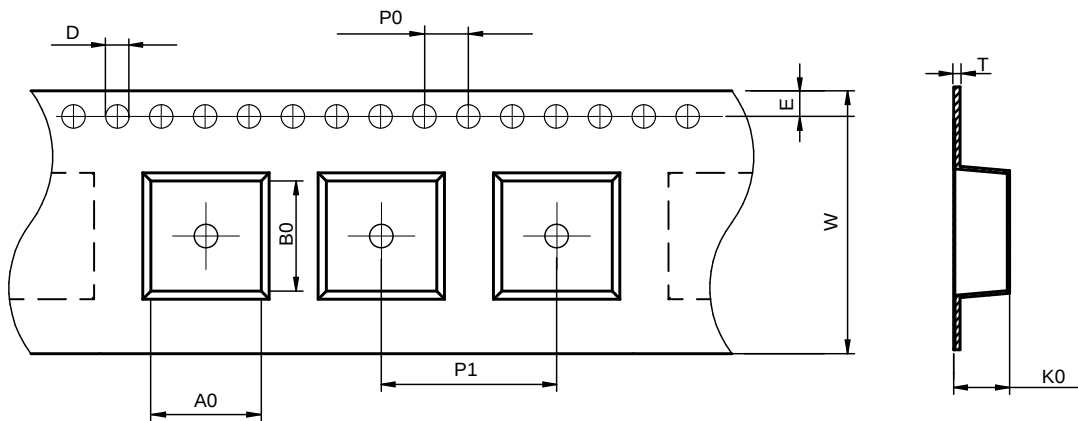
Max temperature: 260 °C .

Max time at max temperature: 30 sec.

Allowed Reflow time: 2x max.

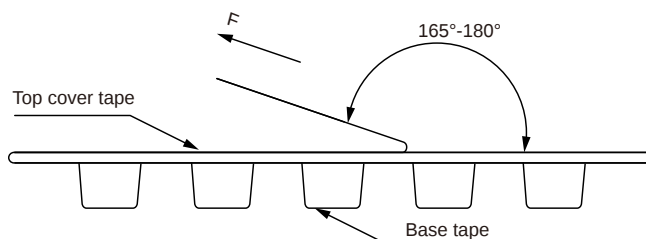
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDA1040HT	10.5 ± 0.1	11.7 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	16.0 ± 0.1	24 ± 0.3	4.4 ± 0.1	1.75 ± 0.1	0.40 ± 0.05

Peel force of top cover tape:

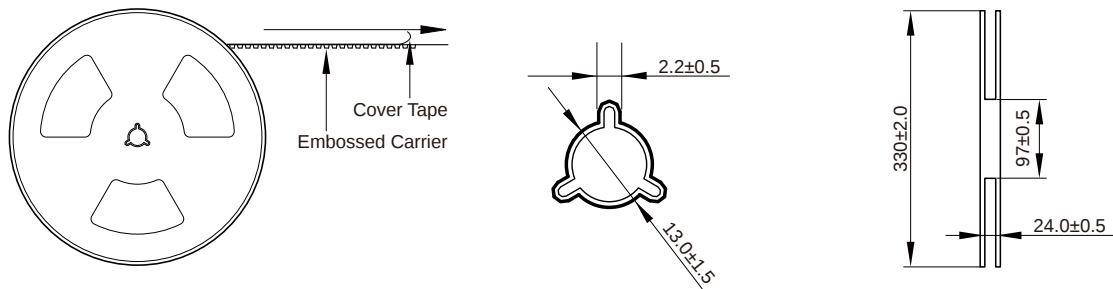


The peel force of top cover tape shall be between 0.1 to 1.3 N

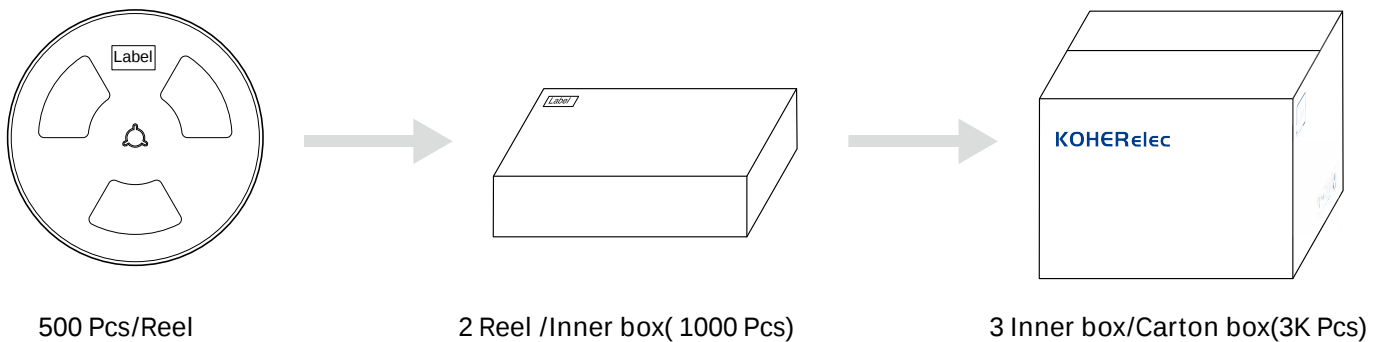
Product Marking:

Marking	KH+Printing Inductance+period)
---------	--------------------------------

Reel Dimension: [mm]



Packaging Quantity:



Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does. As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.